

# MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

## DSK22 THRU DSK210

Product specification

## FEATURES

- Ideal for surface mount applications
- Easy pick and place
- Built-in strain relief
- Low forward voltage drop

## MECHANICAL DATA

- Case: Molded plastic
- Epoxy: UL 94V-0 rate flame retardant
- Metallurgically bonded construction
- Polarity: Color band denotes cathode end
- Mounting position: Any

## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified .

Single phase half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

TYPE NUMBER	DSK22 K22	DSK23 K23	DSK24 K24	DSK25 K25	DSK26 K26	DSK28 K28	DSK29 K29	DSK210 K210	UNITS
Maximum Recurrent Peak Reverse Voltage	20	30	40	50	60	80	90	100	V
Maximum RMS Voltage	14	21	28	35	42	56	63	70	V
Maximum DC Blocking Voltage	20	30	40	50	60	80	90	100	V
Maximum Average Forward Rectified Current See Fig. 1	2.0								A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	50								A
Maximum Instantaneous Forward Voltage at 2.0A	0.55		0.70			0.85			V
Maximum DC Reverse Current at Rated DC Blocking Voltage	0.1				0.02				mA
	5				2				mA
Typical Junction Capacitance (Note1)	170								pF
Typical Thermal Resistance R <sub>JA</sub> (Note 2)	80								C/W
Operating Temperature Range T <sub>J</sub>	-65 — +150								°C
Storage Temperature Range T <sub>STG</sub>	-65 — +150								°C
Marking Code									

### NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Ambient.

**RATING AND CHARACTERISTIC CURVES (DSK22 THRU DSK210)**

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

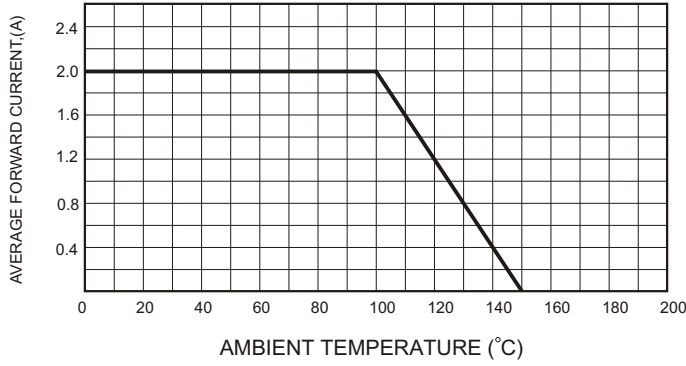


FIG.2-TYPICAL FORWARD CHARACTERISTICS

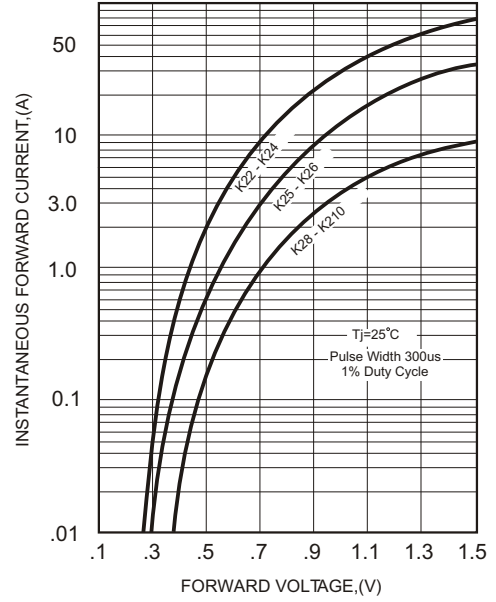


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

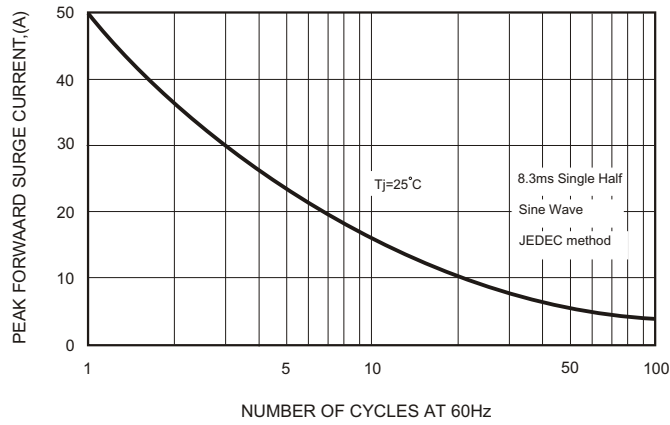


FIG.4-TYPICAL JUNCTION CAPACITANCE

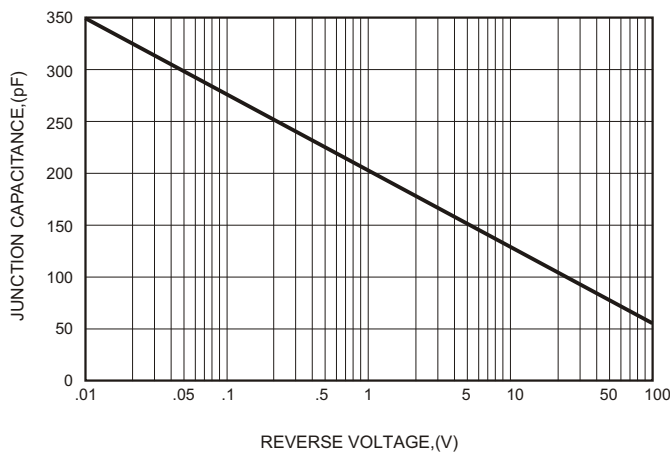
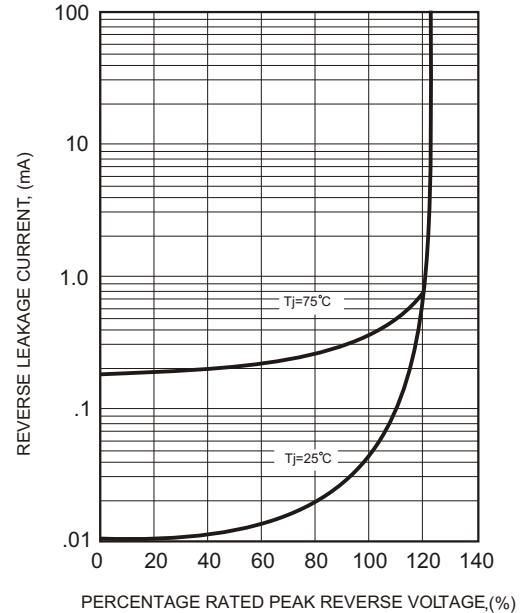
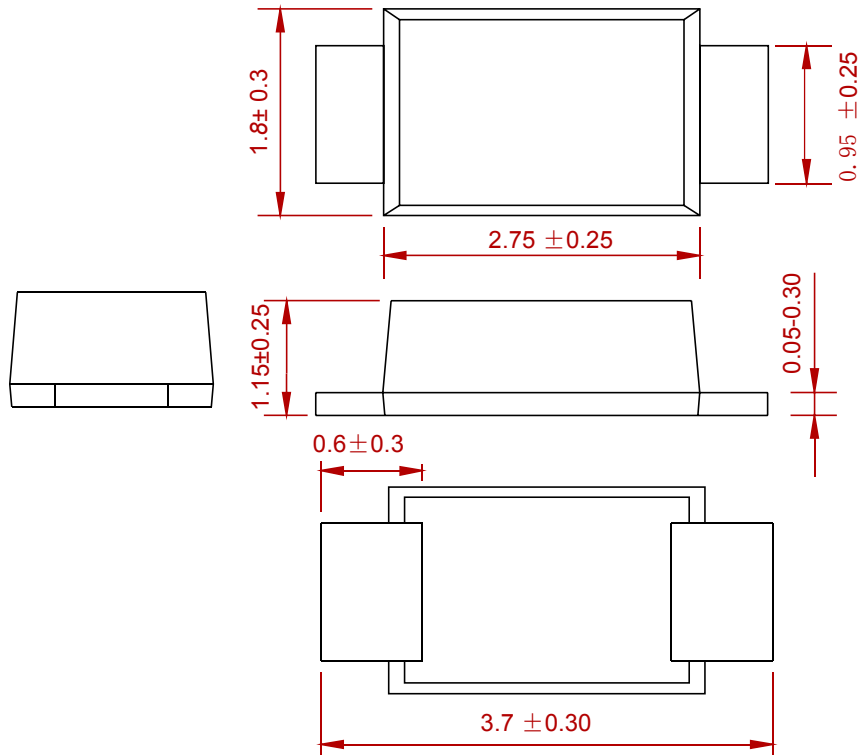


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

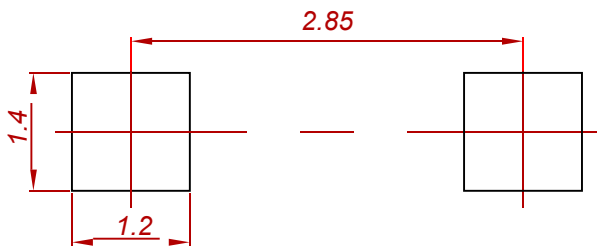


**PACKAGE MECHANICAL DATA**



*Dimensions in millimeters*

**Suggested Pad Layout**



- Note:**
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05$  mm.
  3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
DSK22 THRU DSK210	SOD-123FL	3000

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